Tables 4: Electrical Characteristics (T_j = 25°C, unless otherwise specified)

Symbol	Test Conditions	Quadrant		Value	Unit
I_{GT} (1)	V_D = 12 V R_L = 33 Ω	I - II - III	MAX.	35	mA
V_{GT}		I - II - III	MAX.	1.3	V
V_{GD}	$V_D = V_{DRM}$ R_L = 3.3 kΩ T_j = 150°C	I - II - III	MIN.	0.15	V
I_H (2)	I_T = 100 mA		MAX.	35	mA
I_L	$I_G = 1.2\ I_{GT}$	I - III	MAX.	50	mA
		II		80	
dV/dt (2)	V_D = 67 %V_{DRM} gate open T_j = 150°C		MIN.	300	V/µs
(dI/dt)c (2)	Without snubber T_j = 150°C		MIN.	5.3	A/ms

Table 5: Static Characteristics

Symbol	Test Conditions			Value	Unit
V_T (2)	I_{TM} = 17 A t_p = 380 µs	T_j = 25°C	MAX.	1.55	V
V_{to} (2)	Threshold voltage	T_j = 150°C	MAX.	0.80	V
R_d (2)	Dynamic resistance	T_j = 150°C	MAX.	25	mΩ
I_{DRM} I_{RRM}	$V_{DRM} = V_{RRM}$	T_j = 25°C	MAX.	5	µA
		T_j = 150°C		5.5	mA
	V_{DRM}/V_{RRM} = 400V (at mains peak voltage)	T_j = 150°C		3.5	

Note 1: minimum I_{GT} is guaranted at 10% of I_{GT} max.

Note 2: for both polarities of A2 referenced to A1.

Table 6: Thermal resistance

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case (AC)		D^2PAK	1.2	°C/W
			TO-220AB		
$R_{th(j-a)}$	Junction to ambient	S = 1 cm^2	D^2PAK	45	°C/W
			TO-220AB	60	

S = Copper surface under tab.

Figure 1: Maximum power dissipation versus RMS on-state current (full cycle)

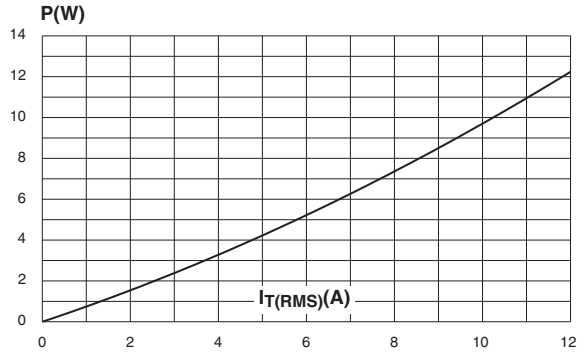


Figure 2: RMS on-state current versus case temperature (full cycle)

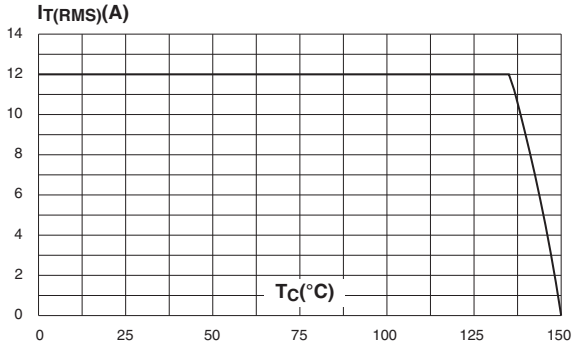


Figure 3: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35µm) (full cycle)

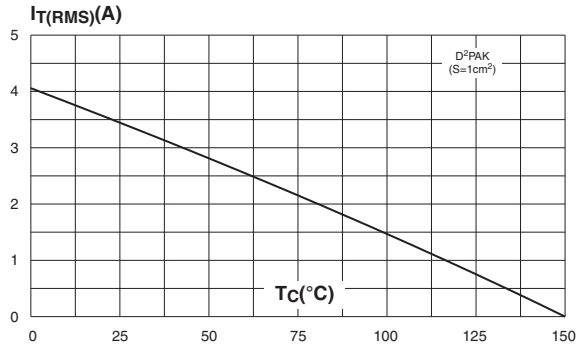


Figure 4: Relative variation of thermal impedance versus pulse duration

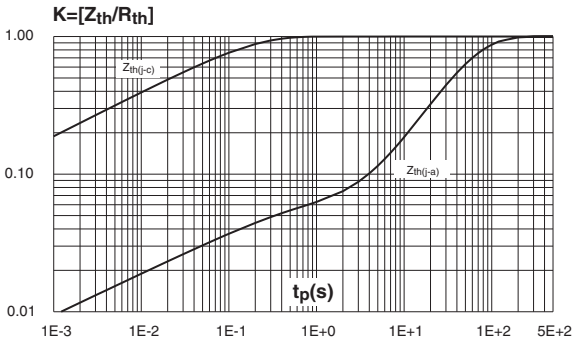


Figure 5: On-state characteristics (maximum values)

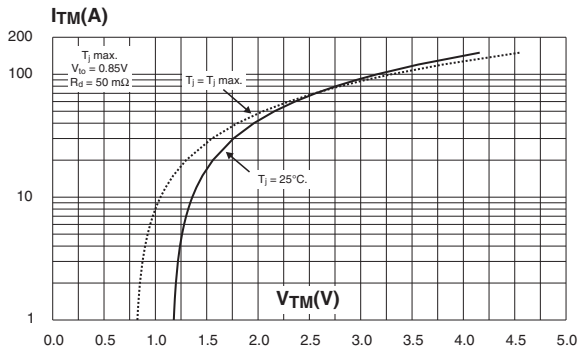


Figure 6: Surge peak on-state current versus number of cycles

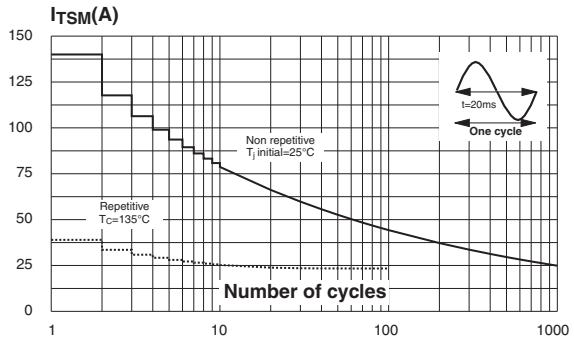


Figure 7: Non-repetitive surge peak on-state current for a sinusoidal pulse with width t_p < 10 ms and corresponding value of I^2t

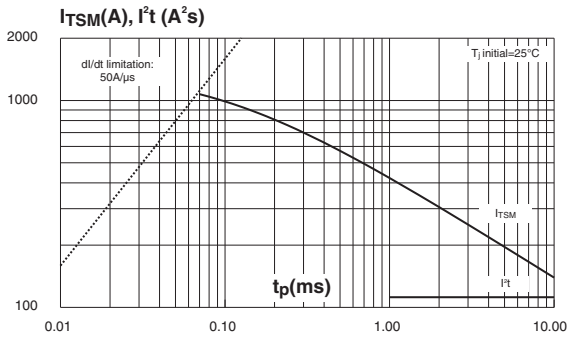


Figure 8: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values)

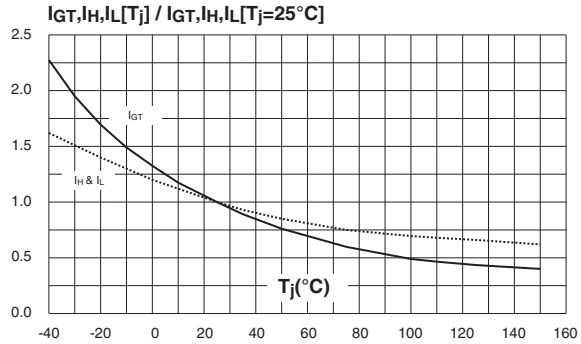


Figure 9: Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values)

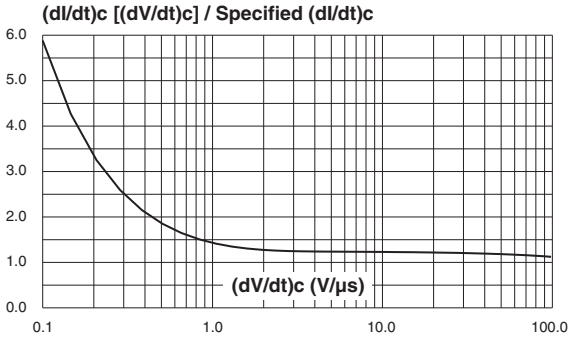


Figure 10: Relative variation of critical rate of decrease of main current versus junction temperature

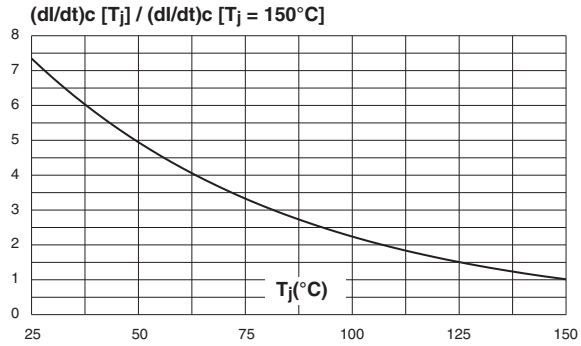


Figure 11: Leakage current versus junction temperature for different values of blocking voltage (typical values)

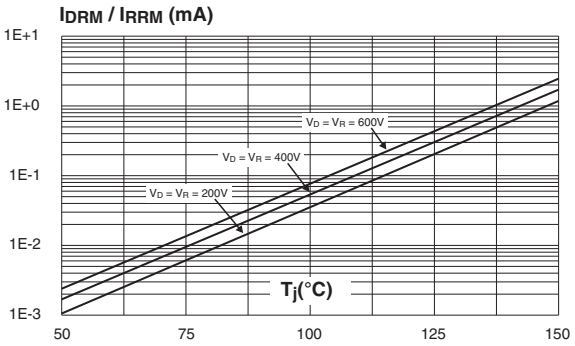


Figure 12: Acceptable repetitive peak off-state voltage versus case-ambient thermal resistance

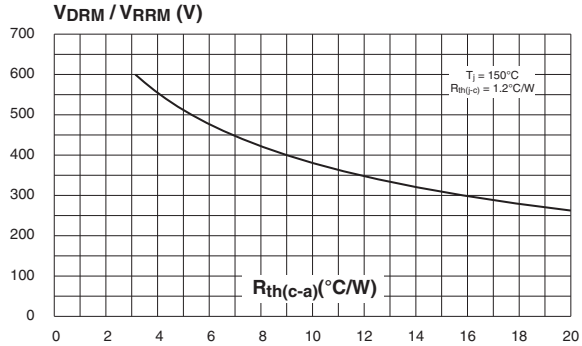


Figure 13: D²PAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 µm)

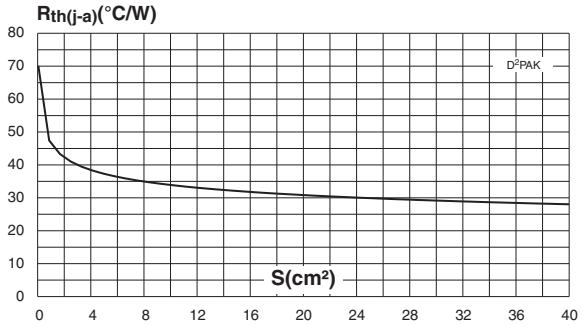


Figure 14: Ordering Information Scheme

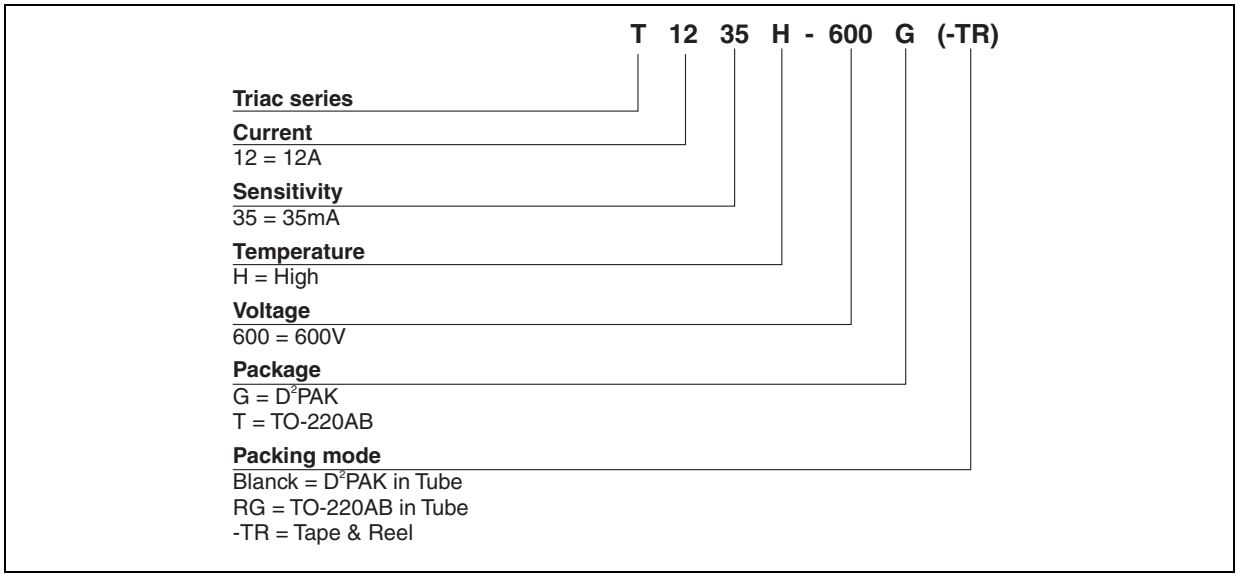
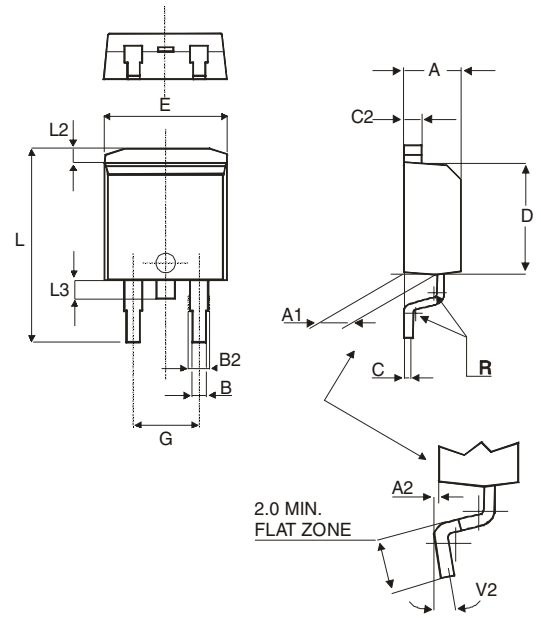


Table 7: Product Selector

Part Numbers	Voltage	Sensitivity	Type	Package
T1235H-600G	600 V	35 mA	Snubberless	D²PAK
T1235H-600T	600 V	35 mA	Snubberless	TO-220AB

Figure 15: D²PAK Package Mechanical Data



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.70		0.93	0.027		0.037
B2	1.25	1.40		0.048	0.055	
C	0.45		0.60	0.017		0.024
C2	1.21		1.36	0.047		0.054
D	8.95		9.35	0.352		0.368
E	10.00		10.28	0.393		0.405
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055
L3	1.40		1.75	0.055		0.069
R		0.40			0.016	
V2	0°		8°	0°		8°

Figure 16: D²PAK Foot Print Dimensions
(in millimeters)

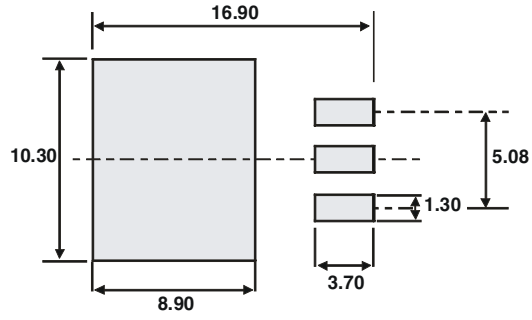
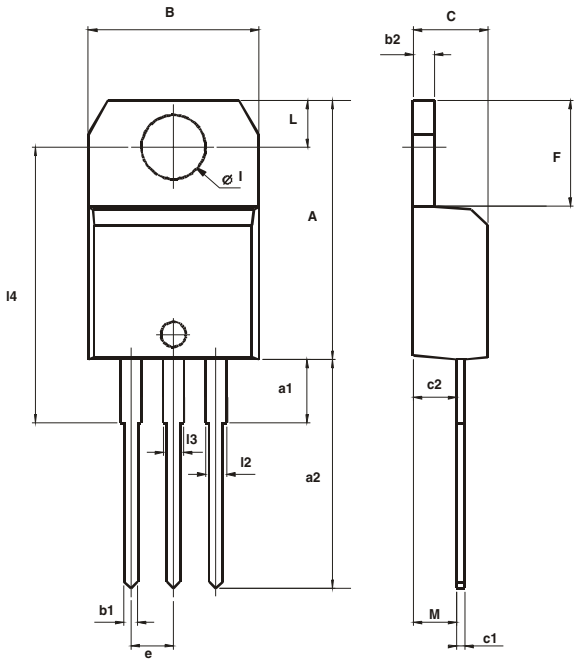


Figure 17: TO-220AB and TO-220AB Insulated Package Mechanical Data



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
I	3.75		3.85	0.147		0.151
l4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
l2	1.14		1.70	0.044		0.066
l3	1.14		1.70	0.044		0.066
M		2.60			0.102	

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Table 8: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
T1235H-600TRG	T1235H600T	TO-220AB	2.3 g	50	Tube
T1235H-600G	T1235H600G	D^2PAK	1.5 g	50	Tube
T1235H-600G-TR	T1235H600G			1000	Tape & reel

Table 9: Revision History

Date	Revision	Description of Changes
Apr-2002	5A	Last update.
13-Feb-2006	6	TO-220AB delivery mode changed from bulk to tube. ECOPACK statement added.